

Title (en)

Circuit board connector for two parallel circuit boards

Title (de)

Leiterkartensteckverbindung für zwei parallele Leiterplatten

Title (fr)

Connexion à fiches de circuits imprimés pour deux plaques conductrices parallèles

Publication

**EP 1973201 A3 20100602 (DE)**

Application

**EP 08001989 A 20080202**

Priority

DE 102007006204 A 20070208

Abstract (en)

[origin: EP1973201A2] The connection has a single-piece, surface-mounted connection unit (1) formed as a quadratic, multi-sided symmetrical base body (10). Notches (15, 17) are provided between two edge areas (14, 16), and a contact support (30) for an electrical signal contact is provided in an inner side of the base body in a third edge area (18) between the notches, where the signal contact points the centre of the base body. The base body is provided with an electrically conducting coating, and the opening width of the notches corresponds to the wall thickness of the base body.

IPC 8 full level

**H01R 13/28** (2006.01); **H01R 13/658** (2011.01)

CPC (source: EP US)

**H01R 12/73** (2013.01 - EP US); **H01R 24/84** (2013.01 - EP US); **H01R 12/52** (2013.01 - EP US); **H01R 12/57** (2013.01 - EP US); **H01R 13/28** (2013.01 - EP US); **H01R 13/6599** (2013.01 - EP US); **H01R 24/50** (2013.01 - EP US)

Citation (search report)

- [AD] US 7118383 B2 20061010 - NAGATA TAKAYUKI [JP], et al
- [A] US 5498167 A 19960312 - SETO MASASHI [JP], et al
- [A] US 2006178022 A1 20060810 - LIU JUN-XIAN [CN]

Cited by

CN105514728A; WO2019201768A1; US11316295B2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA MK RS

DOCDB simple family (publication)

**US 2008194125 A1 20080814**; **US 7513780 B2 20090407**; AT E518278 T1 20110815; CN 101242039 A 20080813; CN 101242039 B 20101215; DE 102007006204 B3 20080417; EP 1973201 A2 20080924; EP 1973201 A3 20100602; EP 1973201 B1 20110727; ES 2369025 T3 20111124; JP 2008198606 A 20080828; JP 4709863 B2 20110629

DOCDB simple family (application)

**US 1958008 A 20080124**; AT 08001989 T 20080202; CN 200810004837 A 20080204; DE 102007006204 A 20070208; EP 08001989 A 20080202; ES 08001989 T 20080202; JP 2008028931 A 20080208